

SEMICONDUCTOR PACKAGE WITH STACKED DIES

ABSTRACT OF THE DISCLOSURE

[0029] A semiconductor package comprising a plurality of leads. Each of the leads defines opposed first and second surfaces, and a third surface which is also disposed in opposed relation to the second surface and laterally offset outwardly relative to the first surface. The semiconductor package further comprises first and second semiconductor dies which each define opposed top and bottom surfaces. Disposed on the top surface of the first semiconductor die are a plurality of bond pads, with bond pads also being disposed on the bottom surface of the second semiconductor die. The bond pads of the first semiconductor die are electrically connected to respective ones of the first surfaces of the leads through the use of conductive bumps. The conductive bumps are also used to electrically connect the bond pads of the second semiconductor die to respective ones of the second surfaces of the leads. An encapsulating portion is applied to and at least partially encapsulates the leads, the first and second semiconductor dies, and the conductive bumps.